L Number	Hits	Search Text	DB	Time stamp
1	2219	134/902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 07:14
2	165	134/77.ccls.	USPAT	2004/10/25 07:21
3	60	134/78.ccls.	USPAT	2004/10/25 07:30
4	102	134/79.ccls.	USPAT	2004/10/25 07:37
5	250	134/140.ccls.	USPAT	2004/10/25 07:46
6	216	134/149.ccls.	USPAT	2004/10/25 07:49
7	143	134/158.ccls.	USPAT	2004/10/25 07:55
8	1022	134/6.ccls.	USPAT	2004/10/25 08:17
9	0	134/22.ccls.	USPAT	2004/10/25 08:17
10	592	134/32.ccls.	USPAT	2004/10/25 08:34
11	467	134/33.ccls.	USPAT	2004/10/25 08:38
12	320	438/690.ccls.	USPAT	2004/10/25 08:46
13	1612	438/692.ccls.	USPAT	2004/10/25 08:48
14	2202	438/690-693.ccls.	USPAT	2004/10/25 08:48
15	1685	438/690-693.ccls. and (cleaning adj5 substrate wafer)	USPAT	2004/10/25 08:50
-	4	("20010044266"|"5738574").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 07:04
-	315	451/66.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 15:30
-	413	451/67.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 15:31
-	914	15/77.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/21 11:03
-	0	15/88.7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/21 11:04
-	232	15/88.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/21 11:07
-	0	15/88.7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/21 11:08
-	613	15/88.3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/21 11:10
-	506	15/102.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/21 11:11
-	10	("4350954" | "5213118" | "5299584" | "5329732" | "5333413" | "5421768" | "5425793" | "5456627" | "5498294" | "5518542").PN.	USPAT	2004/10/21 12:49
-	78	5655954.URPN.	USPAT	2004/10/21 12:51